

(0.635 mm) .025"

QTS SERIES

HIGH-SPEED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QTS

Insulator Material:
Liquid Crystal Polymer
Contact Material:
Phosphor Bronze

Plating:
Au or Sn over
50 μ " (1.27 μ m) Ni
Current Rating:
Contact:
1.8 A per pin
(1 pin powered per row)
Ground Plane:
23.1 A per ground plane
(1 ground plane powered)
Operating Temp:
-55 °C to +125 °C
Voltage Rating:
285 VAC
Max Cycles:
100
RoHS Compliant:
Yes

Board Mates:
QSS

Cable Mates:
SQCD

Standoffs:
SO



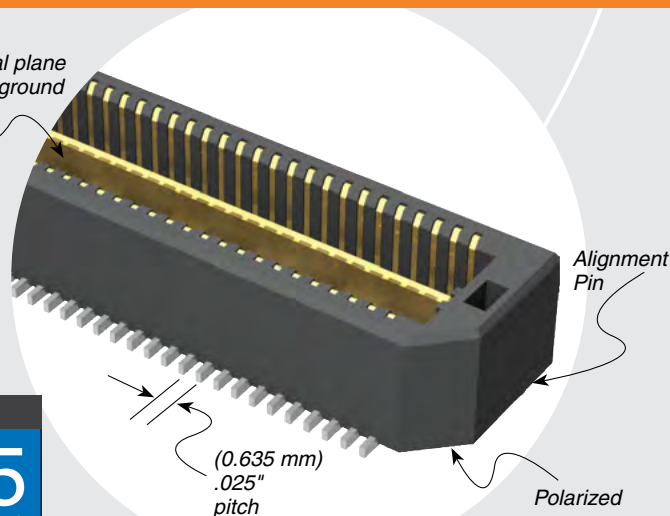
HIGH-SPEED CHANNEL PERFORMANCE

QTS/QSS @ 5 mm Mated Stack Height

Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com
or contact SIG@samtec.com

25
Gbps

Integral metal plane
for power or ground



(0.635 mm)
.025"
pitch

Alignment
Pin

Polarized

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (025-075)
Board Stacking:
For applications requiring more
than two connectors per board
contact ipg@samtec.com

RECOGNITIONS

For complete scope of
recognitions see
www.samtec.com/quality

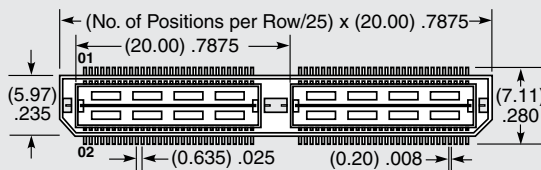


ALSO AVAILABLE (MOQ Required)

- 11 mm & 16 mm stack height
 - 30 μ " (0.76 μ m) Gold
 - Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
 - 100 & 125 positions per row
 - Edge Mount
- Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

QTS	NO. OF POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	D	A	OTHER OPTION
	-025, -050, -075 (50 total positions per bank)	Specify LEAD STYLE from chart.	-F = Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails -L = 10 μ " (0.25 μ m) Gold on Signal Pins and Ground Plane, Matte Tin on tails -C* = Electro-Polished Selective 50 μ " (1.27 μ m) min Au over 150 μ " (3.81 μ m) Ni on Signal Pins in contact area, 10 μ " (0.25 μ m) min Au over 50 μ " (1.27 μ m) Ni on Ground Plane in contact area, Matte Tin over 50 μ " (1.27 μ m) min Ni on all solder tails			-K = (7.00 mm) .275" DIA Polyimide film Pick & Place Pad -TR = Tape & Reel



*Note: -C Plating passes 10 year MFG testing

LEAD STYLE	A	MATED HEIGHT
-01	(4.27) .168	(5.00) .197
-02	(7.26) .286	(8.00) .315

Processing conditions will affect mated height. See SO Series for board space tolerances